

780 D

Inline High-speed Dispensing Equipment



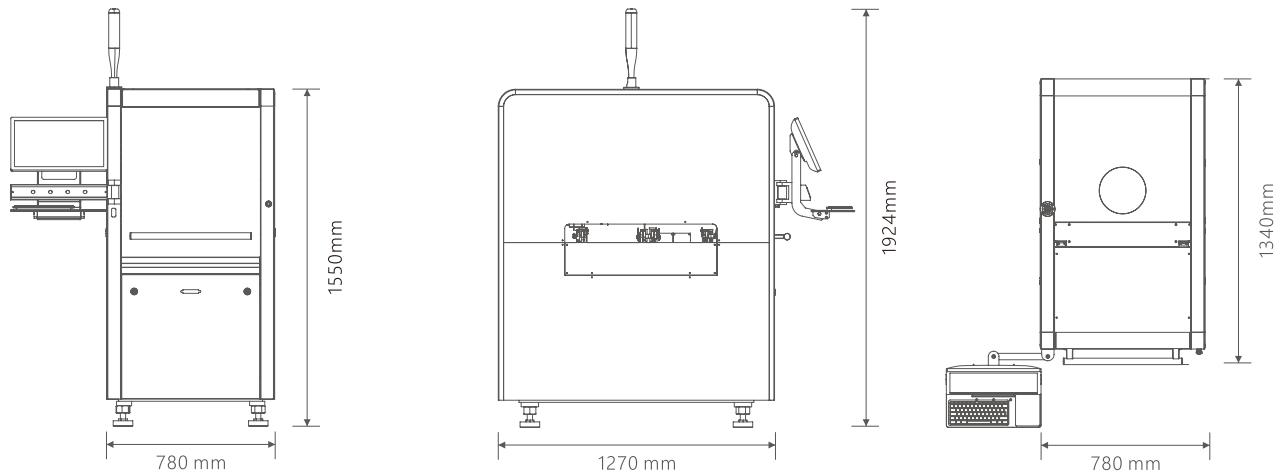
Cencorp 780 D integrates various dispensing technologies and provides a variety of automatic dispensing solutions. It is the best choice in application with complex dispensing path requirement. 780D is mainly used in hot melt adhesive, bottom bonding, surface mount, stack packaging, dam filling, electronic component bonding and material reinforcement in the consumer electronics industry.

- High cost-effective**
- Integrated rack design, stable structure, short downtime and more efficient system operation
 - The use of international top components reduces the failure rate
 - Fewer wearing parts, saving the cost

- Flexibility**
- In-line automatic dispensing equipment capable of handling a wide variety of substrate sizes
 - Flexible configuration of multiple functional modules such as dual rail, dual valve, tilt, bottom heating, etc
 - The universal platform can be applied to a variety of dispensing processes and adhesives, and can be quickly replaced
 - Automatic track width adjustment, compatible with single and double guide rail design
 - Pneumatic valve, piezoelectric valve, screw valve can be adapted, which is more in line with process requirements

- Efficiency**
- Friendly teaching function, more efficient debugging
 - Precise glue volume control to ensure dispensing consistency
 - Accurate intelligent vision system realizes positioning/re-inspection, supports automatic offset correction, and improves the yield of dispensing operations

TECHNICAL DATA



Basic Info Width: 780mm Depth: 1270mm Height: 1550mm Weight: 650kg	Motion System X-travel: 430mm Y-travel: 730mm Z-travel: 50mm U-travel: 90° R-travel: ±30° Repeatability (X, Y): ±0.01 mm Repeatability (Z) : ±0.005mm Repeatability (U,R) : ±0.01°	Vision System Vision Positioning Valve Calibration Vision Inspection: Programmable Datum Identification Time: ≤1s
Basic Function Camera Assist Teaching Dispensing Trajectory: Programmable Track Width Adjustment: Programmable Jet Valve/Needle Cleaning Module Jet Valve/Needle Calibration Module Laser Altimeter Electronic Scale	Processing Capacity Min PCB Size(L*W): 50*50mm Max PCB Size(L*W): 350*450mm(Single Track) 350*210mm(Dual Track) Max Dispensing Range (L*W): 350x450mm PCB Thickness: 0.8-6mm Max PCB Weight: 5.0kg Max Axis Speed (X,Y): 1000mm/s Max Acceleration: 1.0g Conveyor Type: Two-stage Conveyor Speed: Up to 16m/min PCB Transfer Time: 1s (Depending on Run Mode)	Software Function Windows Operating System Standard User Interface Network Connection: Optional User Privilege Management Glue Validity Tracking Glue Change Reminder Non-Dust Cloth Change Reminder Needle/Nozzle Change Reminder Machine Operation Status Monitoring Event Log Transport Protocol: SMEMA Customized Traceability System Local Data Management
Optional Function Track Heating Dual Valve/Dual Track Barcode Scanner FFU External Glue Supply System Touch Screen	Equipment Safety Mechanical Safety: E-stop, Interlock safety doors Electrical Safety: Overpower Protection	
Electrical Service Requirement Voltage: AC220V/50(60)Hz Average Power Cons: 2.5KW	Pneumatic Service Requirement Pressure: Dry clean air 5-7 bar Approx. Air consumption: 90 L/min	Environment Requirement Operating Temperature: 10-40°C Operating Humidity: 30%-85%